

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	TLE8881-2TN	**Issued**	08. April 2022
MA#	MA005710985		
Package	PG-TO220-5-12	**Weight***	2130.04 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	13.951	0.66	0.66	6550	6550
leadframe	inorganic material	phosphorus	7723-14-0	0.277	0.01		130	
	non noble metal	iron	7439-89-6	0.923	0.04		433	
	non noble metal	copper	7440-50-8	921.567	43.27	43.32	432654	433217
wire	non noble metal	aluminium	7429-90-5	4.040	0.19	0.19	1897	1897
encapsulation	inorganic material	zincoxide	1314-13-2	5.622	0.26		2639	
	miscellaneous	miscellaneous	-	22.488	1.06		10557	
	plastics	epoxy resin	-	84.329	3.96		39591	
	inorganic material	silicondioxide	60676-86-0	449.756	21.11	26.39	211149	263936
leadfinish	non noble metal	tin	7440-31-5	24.181	1.14	1.14	11353	11353
plating	inorganic material	phosphorus	7723-14-0	0.008			4	
	non noble metal	nickel	7440-02-0	3.285	0.15	0.15	1542	1546
solder	non noble metal	tin	7440-31-5	0.188	0.01		88	
	noble metal	silver	7440-22-4	0.234	0.01		110	
	non noble metal	lead	7439-92-1	8.954	0.42	0.44	4204	4402
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		83	
	non noble metal	iron	7439-89-6	0.590	0.03		277	
	non noble metal	copper	7440-50-8	589.466	27.67	27.71	276739	277099
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com